

Title (en)
BUS BAR ASSEMBLY

Title (de)
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Title (fr)
ENSEMBLE BARRE OMNIBUS

Publication
EP 1155420 A4 20040630 (EN)

Application
EP 99909545 A 19990222

Priority
US 9903804 W 19990222

Abstract (en)
[origin: WO0051141A1] A bus bar assembly (10) with improved solderability comprises a soldering island (70) with a central soldering opening (64) surrounded by thermal barrier openings (66).

IPC 1-7
H05K 1/02

IPC 8 full level
H05K 1/02 (2006.01); **H05K 3/34** (2006.01); **H05K 3/20** (2006.01)

CPC (source: EP)
H05K 1/0201 (2013.01); **H05K 3/3447** (2013.01); **H05K 1/0263** (2013.01); **H05K 3/202** (2013.01); **H05K 2201/062** (2013.01); **H05K 2201/09118** (2013.01); **H05K 2201/0969** (2013.01); **H05K 2201/10272** (2013.01)

Citation (search report)

- [Y] US 3372308 A 19680305 - NOSCHESE ROCCO J, et al
- [Y] WO 9833365 A1 19980730 - ERICSSON TELEFON AB L M [SE]
- [A] US 5832602 A 19981110 - UEZONO KOUICHI [JP], et al
- [Y] "CROSSED TWIN CIRCLE HEAT BLOCKAGE", IBM TECHNICAL DISCLOSURE BULLETIN, IBM CORP. NEW YORK, US, vol. 36, no. 11, 1 November 1993 (1993-11-01), pages 245 - 246, XP000424849, ISSN: 0018-8689
- See references of WO 0051141A1

Designated contracting state (EPC)
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